

<b>PCN Number:</b>	20131203000A		<b>PCN Date:</b>	May 23, 2018	
<b>Title:</b>	Conversion to Cu bond wire				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services		
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>	Part number change			
<b>PCN Details</b>					
<b>Description of Change:</b>					
Revision A is to remove select devices in the Product Affected Section (with <del>strikethrough</del> ) and highlighted in yellow. These devices were inadvertently added and not affected by this change.					
Texas Instruments is pleased to announce the qualification of Cu as a bond wire option for the selected devices shown below. All listed devices will remain in current assembly facility and there will be no other BOM changes.					
<b>Reason for Change:</b>					
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Changes to product identification resulting from this PCN:</b>					
None					
<b>Product Affected</b>					
<del>TRF3705IRGER</del>	<del>TRF3705IRGET</del>	TRF37T05IRGER	TRF37T05IRGET		

<b>Qualification Data</b>			
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
<b>Qual Vehicle: TRF37T05IRGE (MSL 2-260C)</b>			
<b>Package Construction Details</b>			
Assembly Site:	Clark-AT	Mold Compound:	4208625
# Pins-Designator, Family:	24-RGE, QFN	Mount Compound:	4207768
Lead Finish	NiPdAuAg	Bond Wire:	0.80Mil Cu

<b>Qualification:</b> <input type="checkbox"/> <b>Plan</b> <input checked="" type="checkbox"/> <b>Test Results</b>		
Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	Side by Side (Au vs. Cu)	Pass
ESD CDM	+/- 250V, 500V	3/0
ESD HBM	+/- 500V, 1000V, 1500V	3/0
Latch-up	(per JESD78)	6/0

<b>Reference Qualification Data</b>				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
<b>Qual Vehicle: CDC750RGC (MSL 3-260C)</b>				
Package Construction Details				
Assembly Site:	Clark AT	Mold Compound:	4208625	
# Pins-Designator, Family:	64-RGC, QFN	Mount Compound:	4207768	
Lead Finish	NiPdAu	Bond Wire:	0.8mil Cu/0.8mil Au	
<b>Qualification:</b> <input type="checkbox"/> <b>Plan</b> <input checked="" type="checkbox"/> <b>Test Results</b>				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls, 3 units min	Pass	Pass	Pass
Bond Pad Cratering Check		Pass	Pass	Pass
Bond Pull	76 Wire, 3 units min	Pass	Pass	Pass
Notes   ** - Preconditioning sequence: Level 3-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>